

Thermal conductive pad 3.2W/mK, 100x100mm

Reference: AM1629
EAN13: -
HS code: 38249996



Product attributes:

Thickness: 0.5 mm, 1.0 mm, 1.5 mm, 2.0 mm, 2.5 mm, 3.0 mm, 4.0 mm, 5.0 mm

Product features:

Color: Gray
Max. operating temperature: 260 °C
Thermal conductivity: 3.2 W/mK

Product description:

Thermal conductive pad for heat sinks with thermal conductivity up to 3.2W/mK. The pad is designed to ensure better heat transfer between the heat source - electronic component and its heat sink. It fills the unevenness between the surface of the heat sink and the surface of the cooled component and thus increases the heat transfer to the heat sink, which then has a greater cooling efficiency. By using a heat transfer pad, you will improve the overall cooling efficiency and extend the life of the cooled components. Suitable for all semiconductors (LEDs), processors, graphics cards, memory modules and more. The pad is not electrically conductive.

Thermal conductivity: 3.2W/mK

Minimum operating temperature: -40°C

Maximum operating temperature: 260°C

Colour: grey

Weight:

0.5mm - 11g
1mm - 20g
1.5mm - 28.5g
2mm - 38g
2.5mm - 47g
3mm - 56g
4mm - 76g
5mm - 94g

